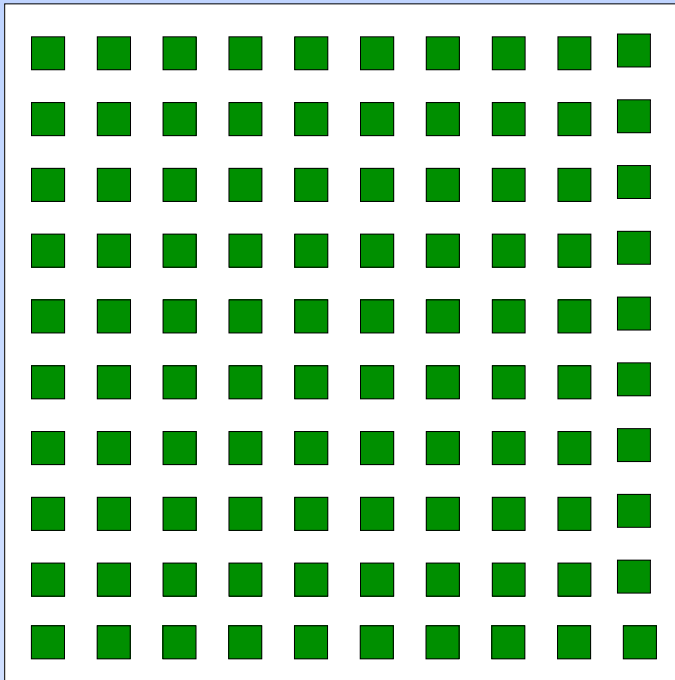


# Networks on Chip

10 processors



10 processors

Axel Jantsch

Royal Institute of Technology, Stockholm

December 11, 2002

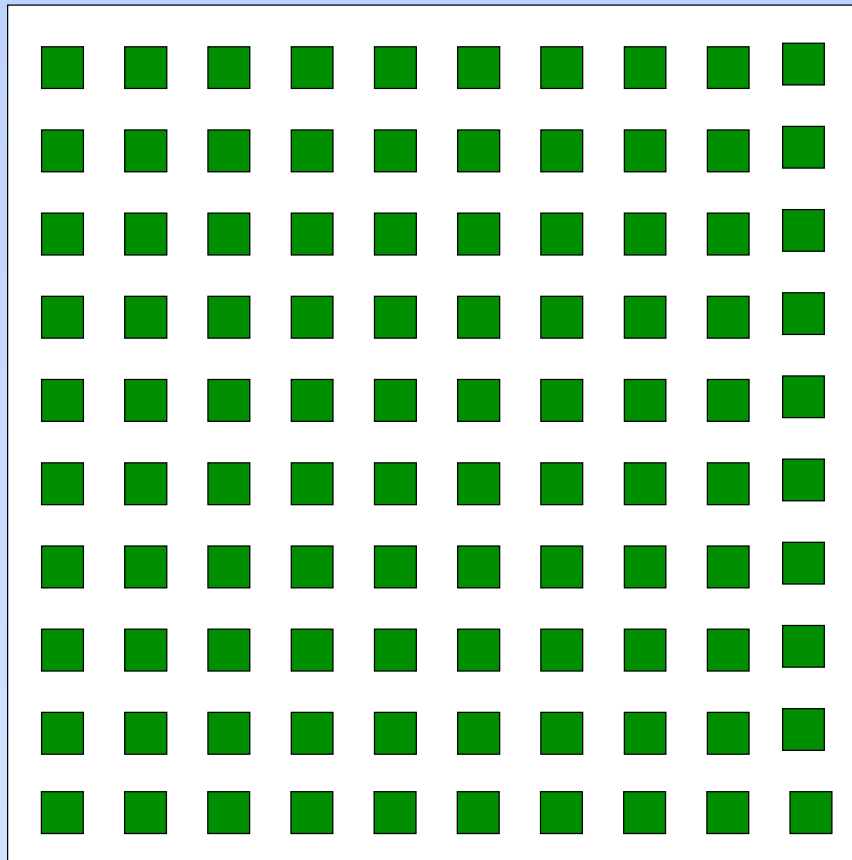
# Overview

- Introduction
- NoC Architecture
- NoC Design Methodology



# The Challenge

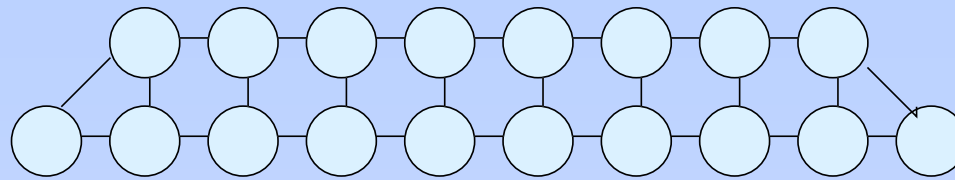
10 processors



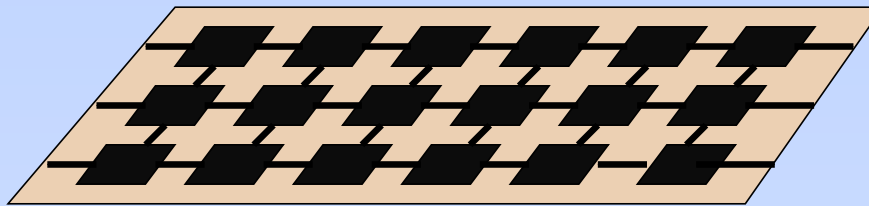
10 processors

# Gates	# Processors	Year
6 M	4	2000
24 M	16	2003
96 M	64	2006
384 M	256	2009

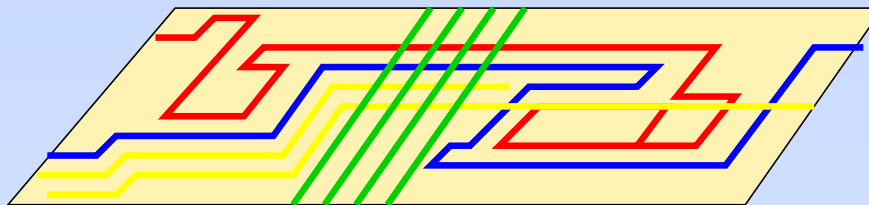
# Functions, Architecture, and Physics



Concurrent processes



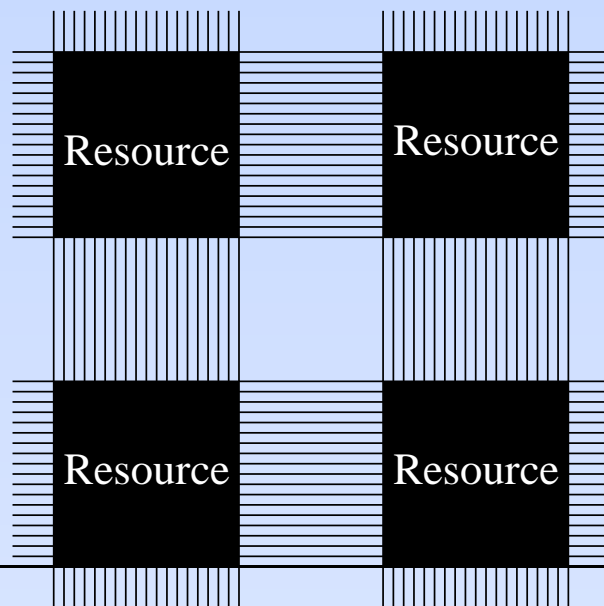
Large number of resources



Physical issues

## Challenge Areas: Physical Issues

- Deep submicron effects, noise, signal integrity
- Interconnect
- Power consumption, power delivery
- Clock distribution
- Memory integration (50-80% of the chip)

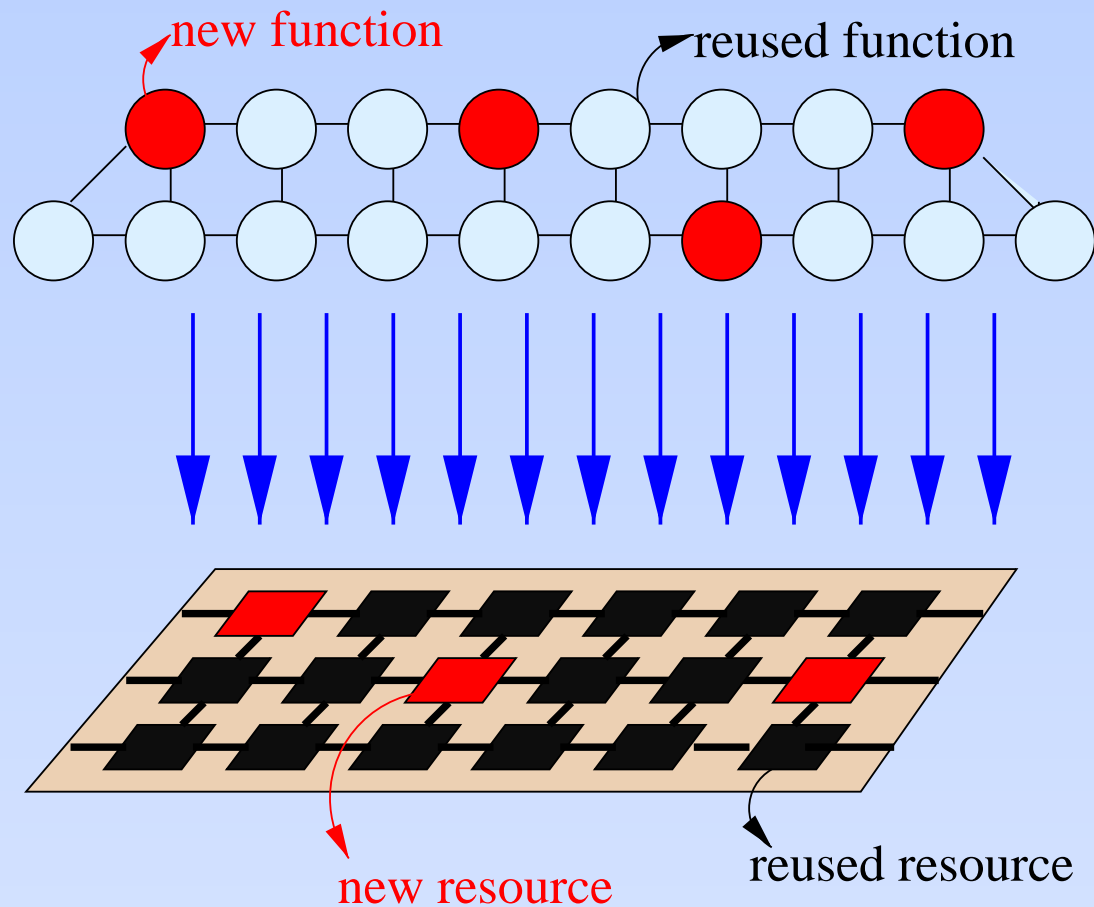


Scenario:

- 60 nm CMOS
- $22 \times 22$  mm Chip size
- $2 \times 2$  mm resource size
- 300 nm minimum wire pitch
- 6600 wires between two resources on each metal layer

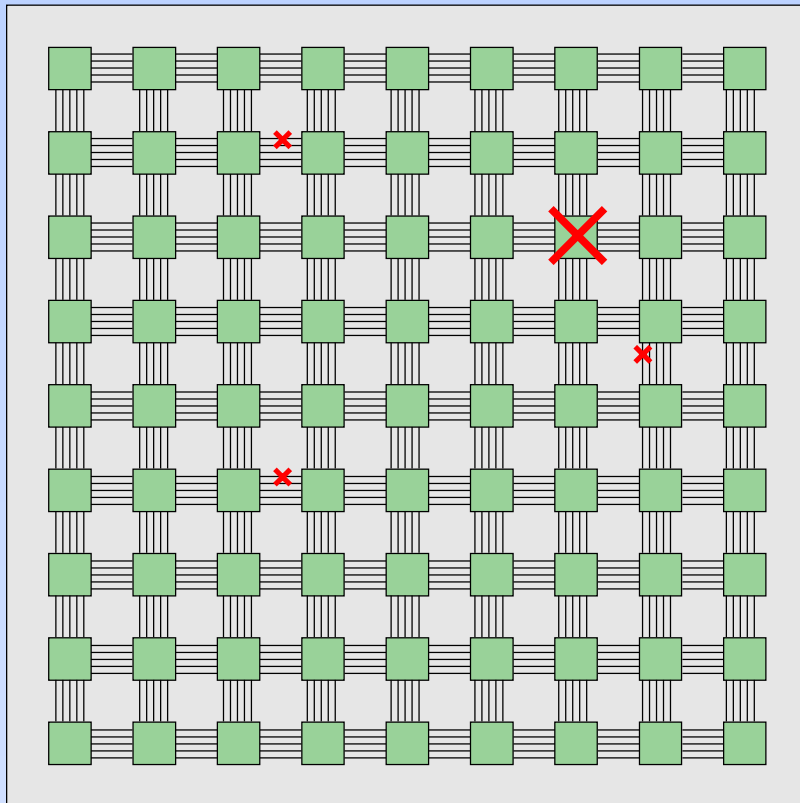


## Challenge Areas: Methodology



- Specification techniques of concurrent activities
- Performance analysis
- Reuse and Integration of both functions and components

## Challenge Areas: Run Time Services



- Monitoring
- Fault-tolerance,
- Diagnostics
- Fault recovery
- Dynamic resource management



## Challenge Areas: Configurability

A sensible trade-off between efficiency and generality is critical.

- Configurability of communication resources from the data link to the application layer
- Configurability of resources (processors, DSPs, FPGAs, etc.)
- When and who?
  - ★ Design-time configuration: Platform  $\Rightarrow$  Product
  - ★ Static product configuration: Once for a product
  - ★ Dynamic reconfiguration: Programming of the product

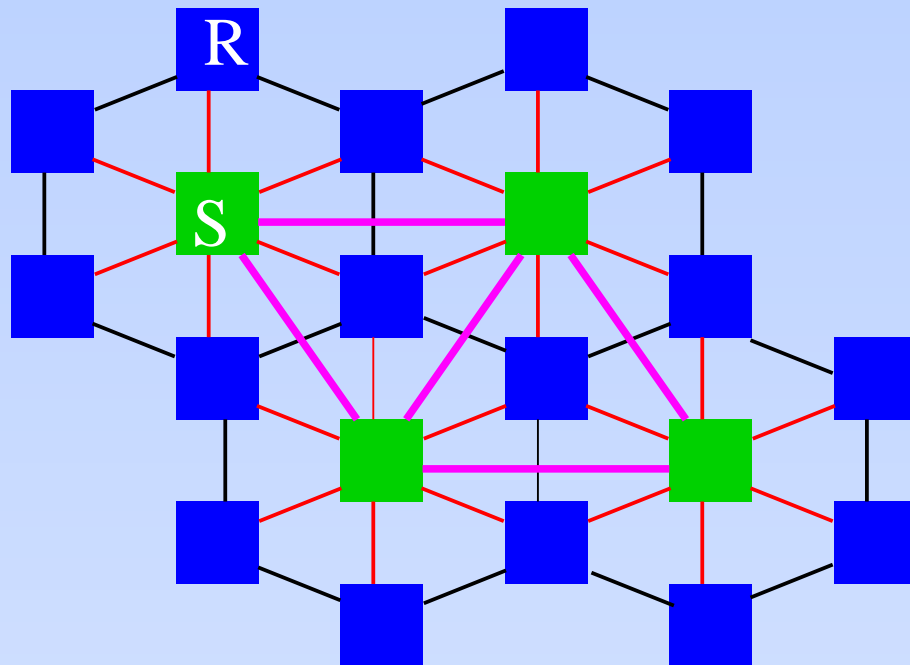


# NoC Architecture

- Topology
- Switch Architecture
- Data link layer
- Network layer
- Transport layer
- Application layers
- Regions

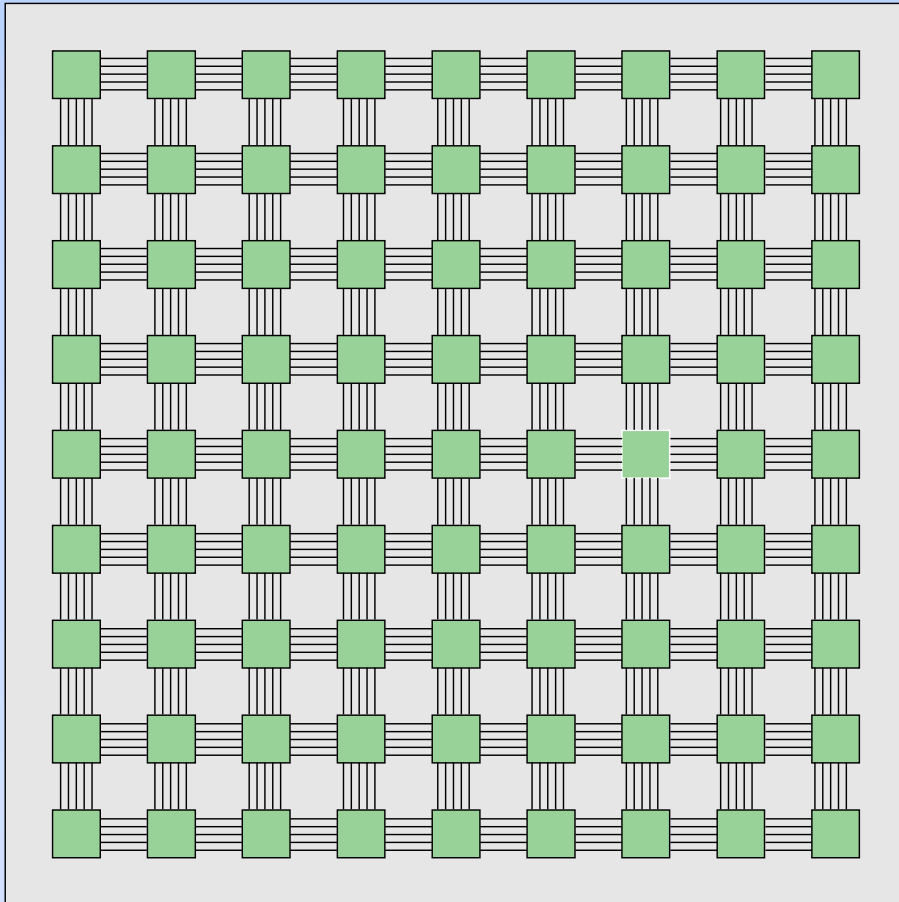


## Topology: Honeycomb



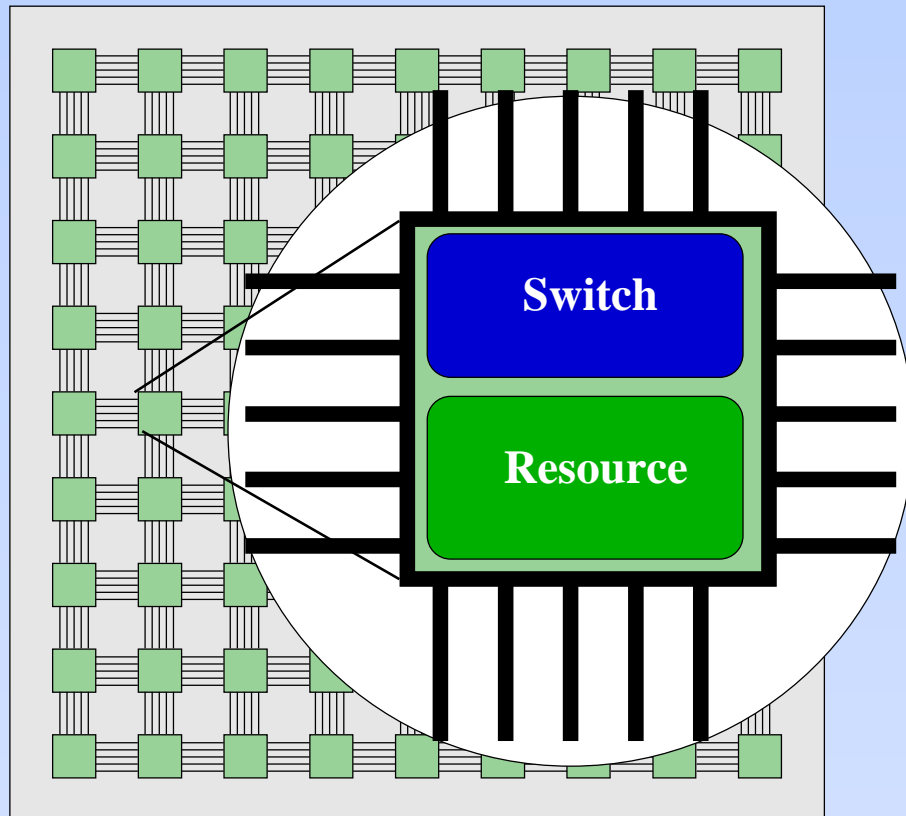
- Resource-to-switch ratio: 3
- A switch is connected to 6 resources and 6 switches
- A resource is connected to 3 switches and 3 resources
- Wiring intense topology
- Max number of hops grows with  $n/3$

## Topology: Mesh



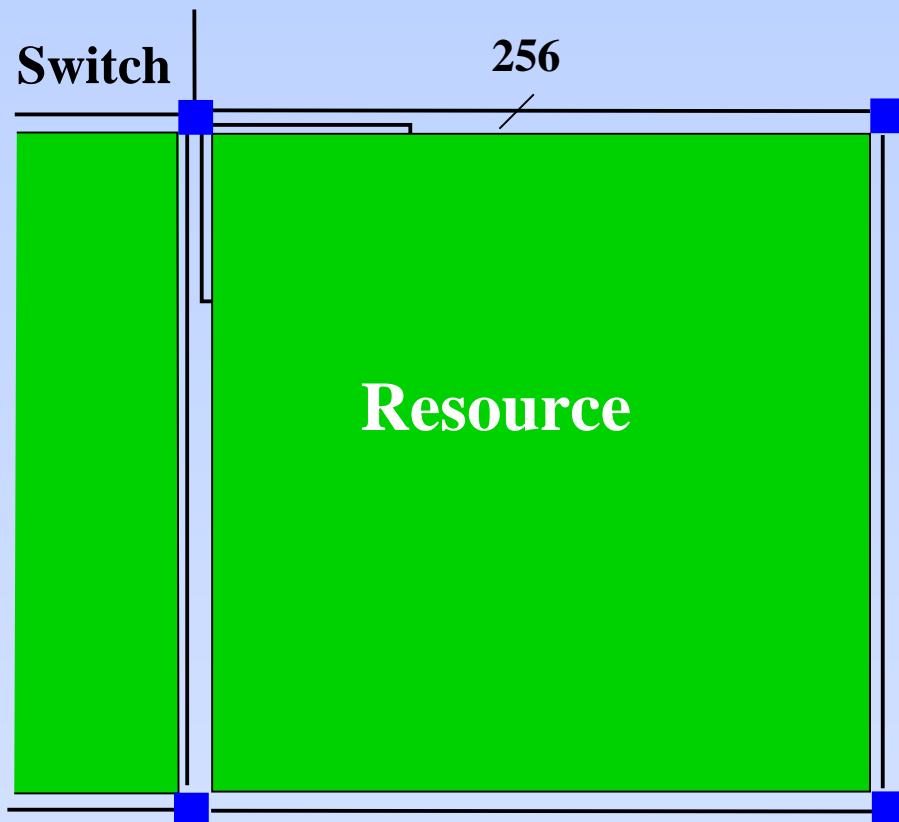
- Resource-to-switch ratio: 1
- A switch is connected to 4 switches and 1 resource
- A resource is connected to 1 switch
- Max number of hops grows with  $2n$

## The Node in a Mesh



- How large are resources and the switches?
- What is the best geometry of switch and resource?
- How many wires and how long?

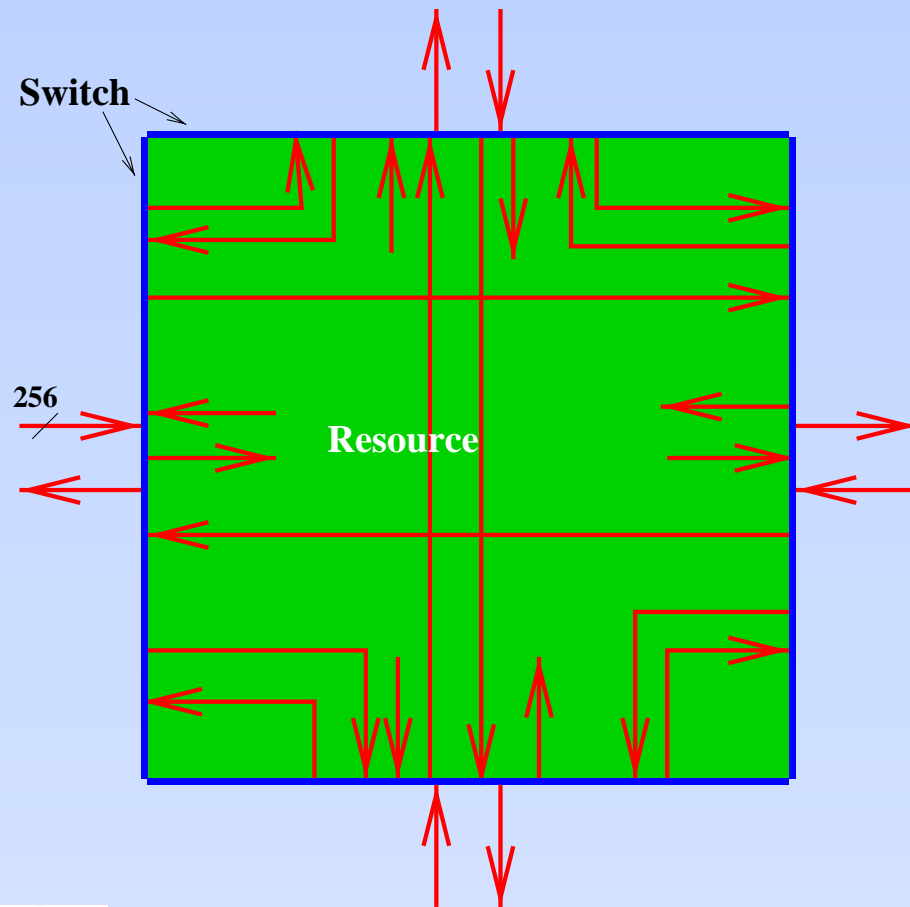
# Square Switch



## Scenario:

- $60nm$  CMOS
- $22mm \times 22mm$  chip size
- $300nm$  minimal wire pitch
- $2mm \times 2mm$  resource
- $100\mu m \times 100\mu m$  switch
- switch-to-switch connection: 256 wires
- switch-to-resource connection: 256 wires

# Thin Switch



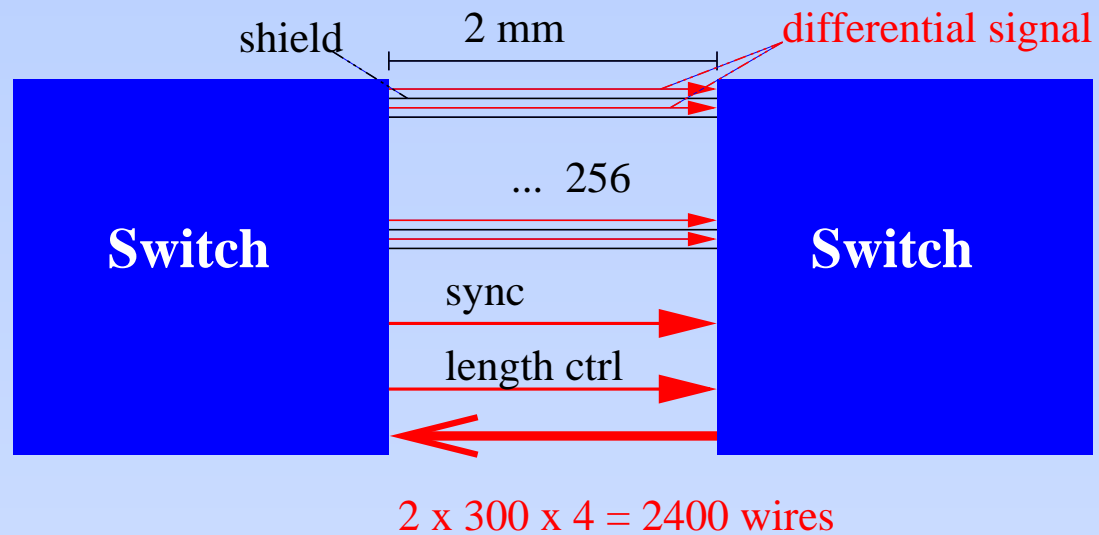
## Scenario:

- 60nm CMOS
- 22mm × 22mm chip size
- 600nm minimal wire pitch for top layers
- 2mm × 2mm resource
- 4 × 50μm × 2000μm switch
- switch-to-switch connection: 512 wires
- switch-to-resource connection: 512 wires





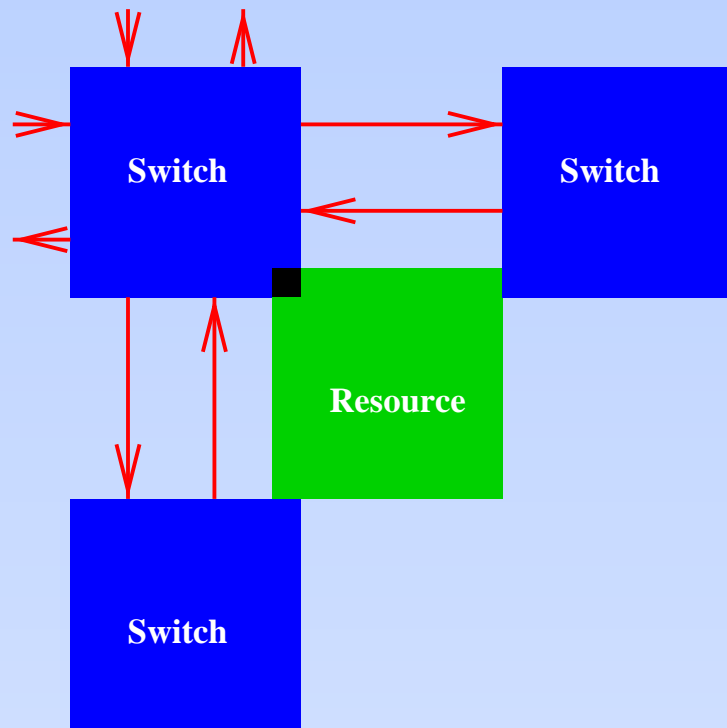
# Physical Layer



Parameters:

- Physical distance
- Number of lines
- Activity control
- Buffers and pipelining

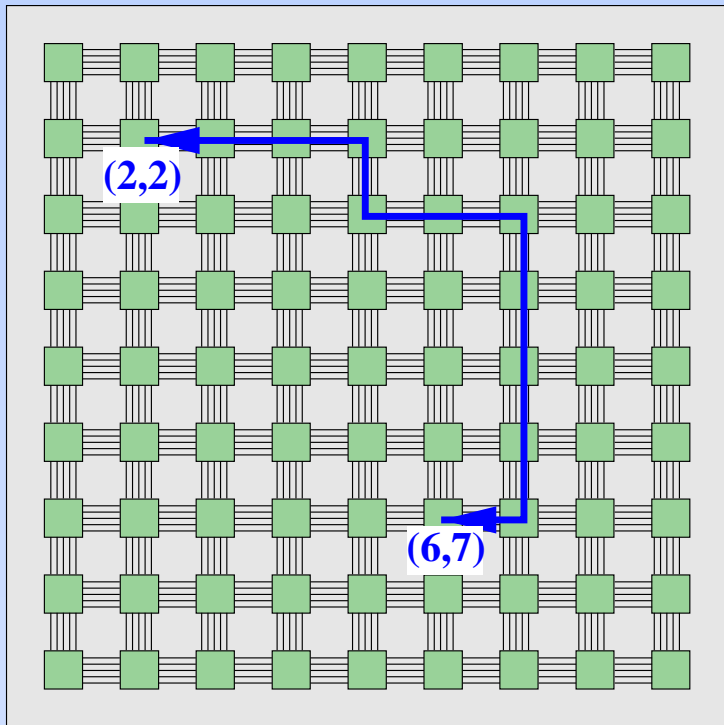
# Data Link Layer



Parameters:

- Line frequency versus switch frequency (word versus cell)
- Buffering
- Error correction
- Power optimization; e.g. avoid activity and power optimized encoding

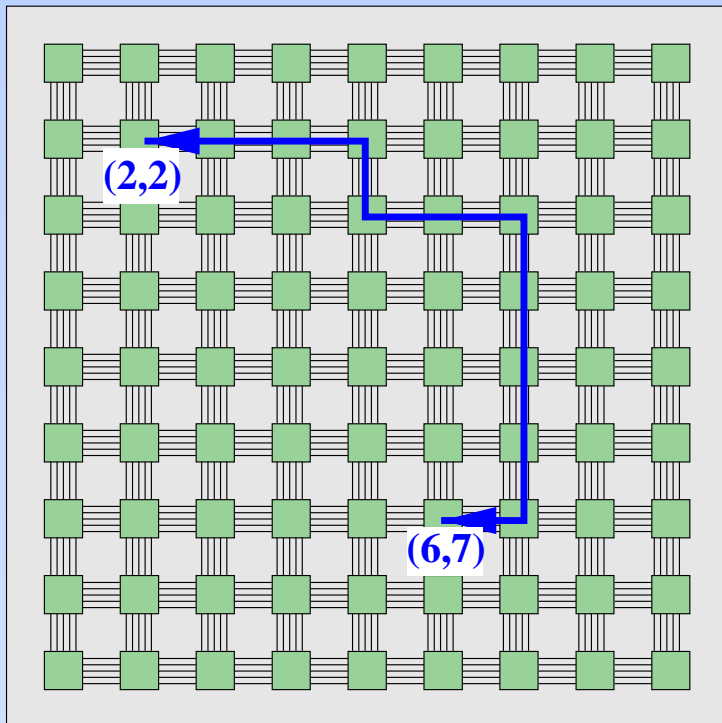
# Network Layer



Parameters:

- cell size versus packet size
- Network address scheme, e.g. 4 + 4 bit for  $16 \times 16$  resources
- Routing algorithm
- Priority classes: e.g. 2 classes:
  1. high priority, fixed delay cells
  2. low priority, best effort delay cells
- Error correction

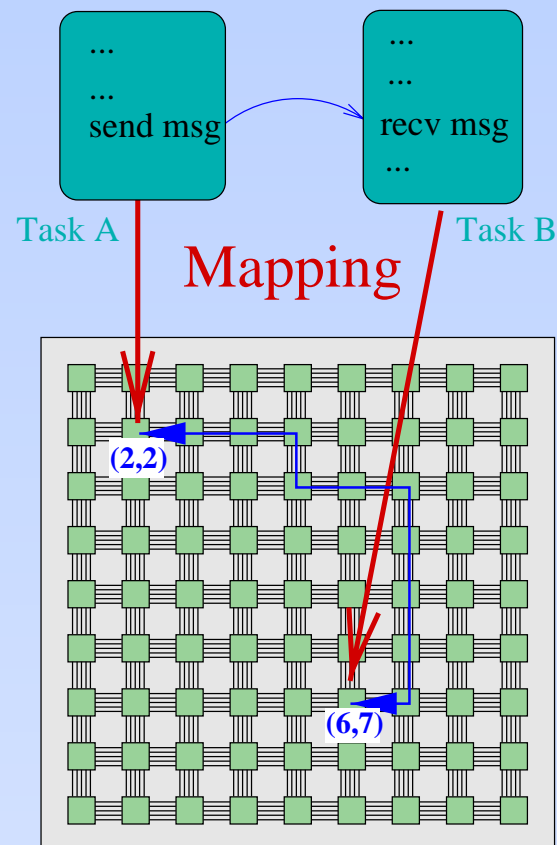
# Transport Layer



Parameters:

- Message size versus cell size
- Virtual channels with traffic profiles
- Signaling
- Priority classes of channels, e.g.
  1. constant bit rate traffic
  2. varying bit rate traffic
- Network resource management
- Error correction

# Application Layers



Interprocess communication at the task level:

- send / receive for individual messages
- open; write/read; close for channel based communication

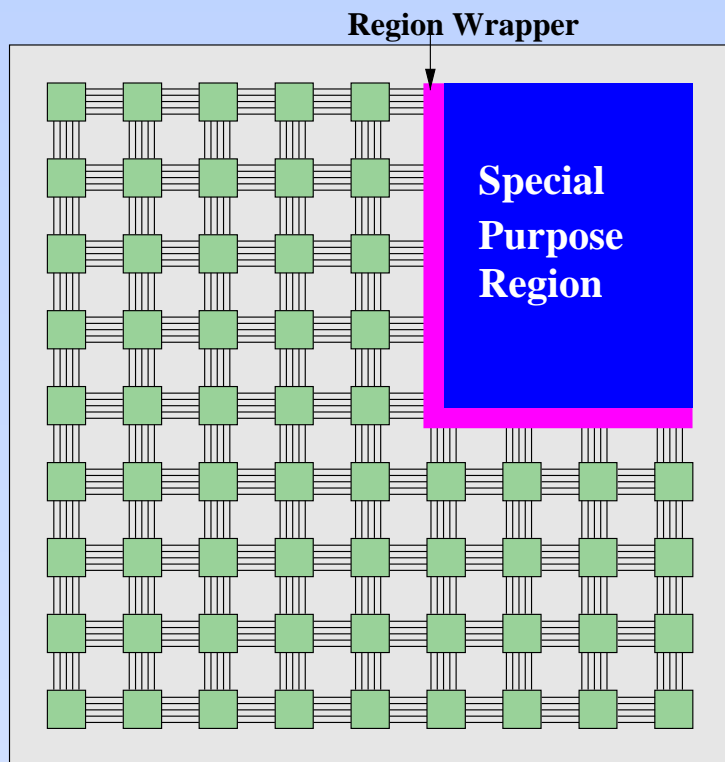
Mapping issues:

- Assigning tasks to resources
- Translating task addresses to resource/task addresses
- Establishing and closing channels
- Static allocation versus dynamic allocation

# Regions

Parameters:

- Not all resources have the same size; e.g.
  - ★ Memory
  - ★ FPGA regions
  - ★ Special purpose architectures like multiprocessors
  - ★ mixed signal parts
- A region wrapper makes the region transparent
- The region wrapper can be
  - ★ at several protocol layers,
  - ★ in hardware or software
  - ★ local or distributed



# NoC Operating System

- Monitoring
  - ★ Utilization of resources and switches
  - ★ Power consumption
  - ★ Statistics (errors, cells, etc.)
- Communication services (transport, presentation and application layers)
- Resource allocation and load migration
- Diagnostics and fault recovery
- Power management
- Development support services
  - ★ Libraries for run-time services
  - ★ Compilers, linkers and simulators

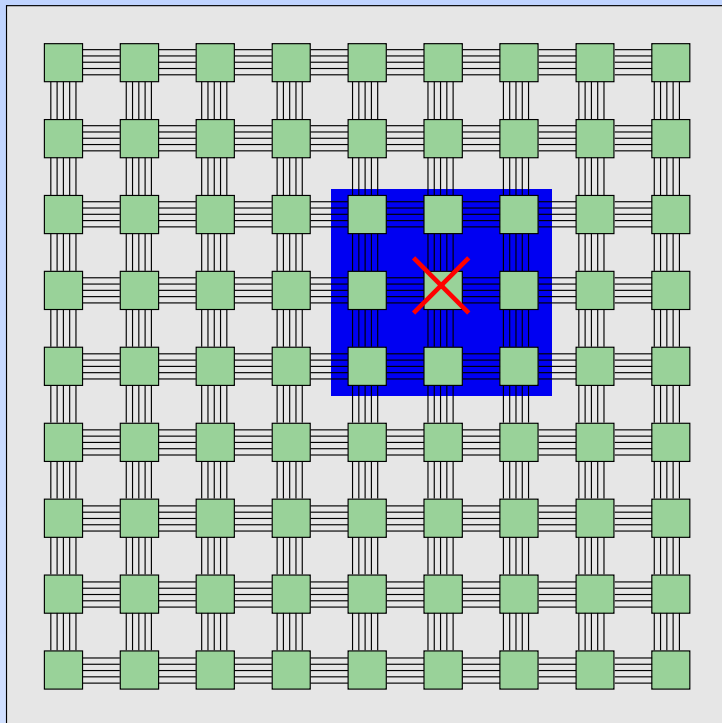
# Dynamic Fault Handling Example

Assumptions:

- NoC-OS makes run-time diagnostics
- NoC-OS can identify faulty parts
- Network layer protocol can be reconfigured at run-time

If a resource becomes faulty:

1. NoC-OS detects a faulty resource
2. NoC-OS defines a new region to isolate the faulty resource
3. NoC-OS reconfigures the Network layer protocol to route around the faulty resource





## Summary - NoC Architecture

- The NoC Architecture defines
  - ★ the communication infrastructure
  - ★ the resource-to-network interface
  - ★ the network services
- Strict layering of communication protocols and services allows
  - ★ the separation of the network backbone from the resources
  - ★ combination of different features and functionality at different levels
  - ★ the customization of a generic platform into an efficient product

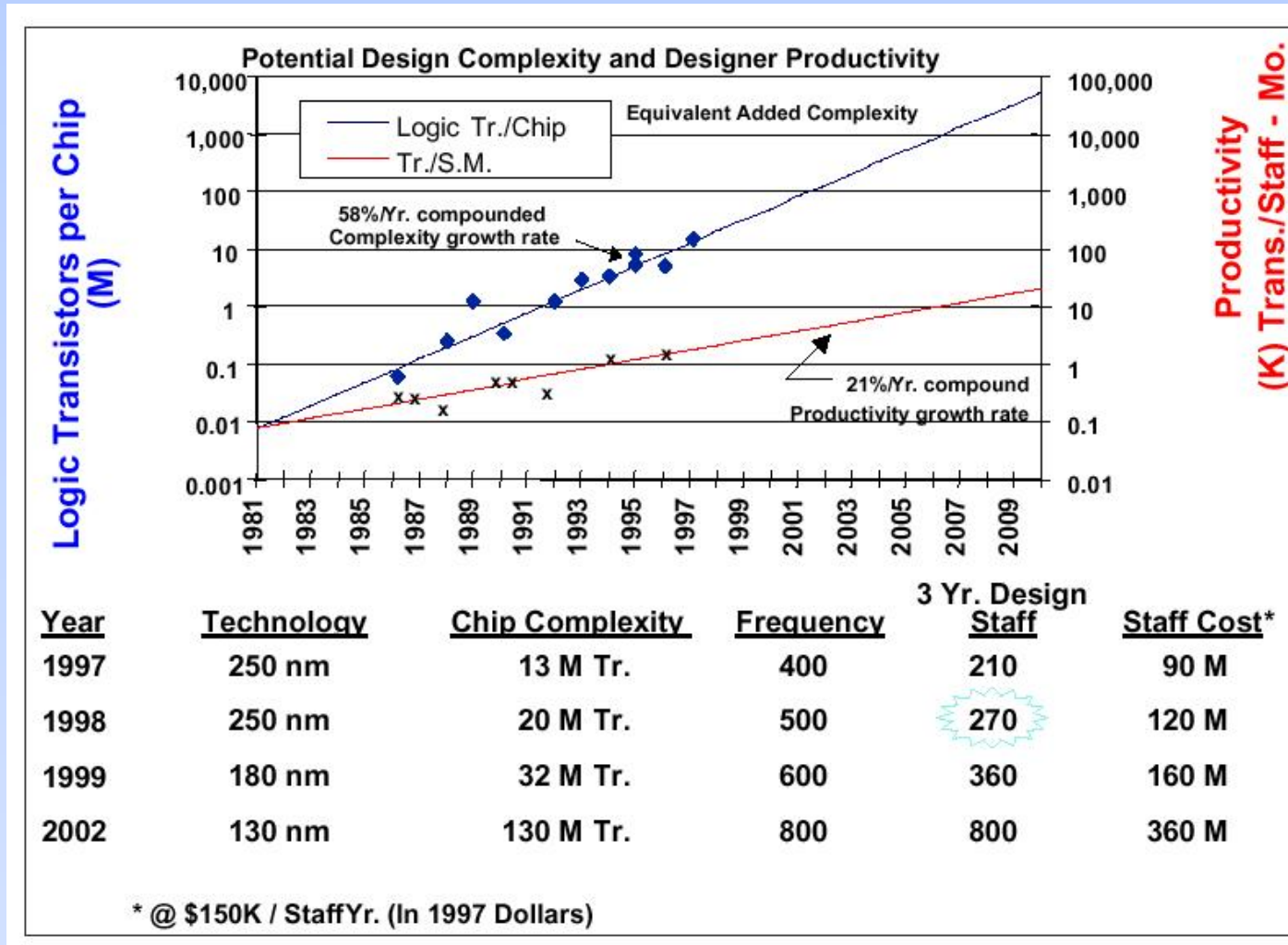


# NoC Design Methodology

- Design Productivity Gap
- Arbitrary Composability
- Reuse
- Predictability



# Design Productivity Gap



International Technology Roadmap for Semiconductors 1999



# Superexponential Increasing Design Complexity



International Technology Roadmap for Semiconductors 1999



# Arbitrary Composability

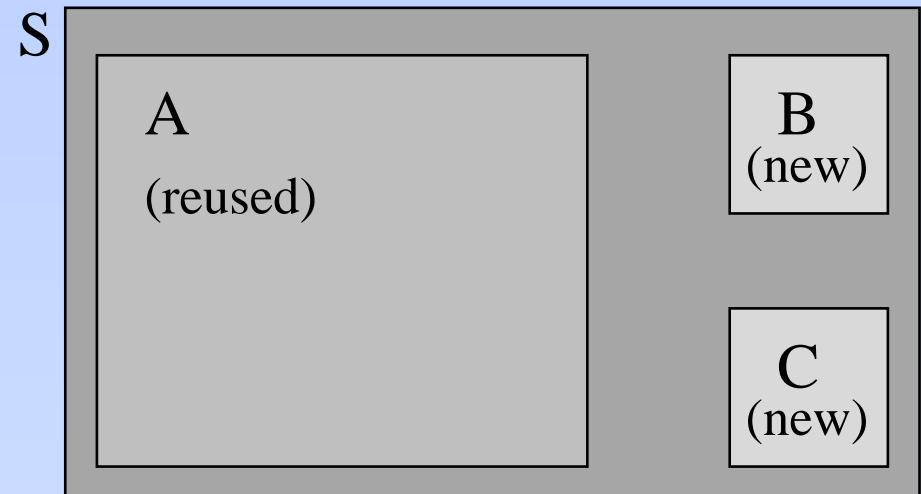
Given a set of components  $C$  and combinators  $O$ .

Let  $A_1$  be a component assemblage.

$(C, O)$  is **arbitrary composable** if

$$A_1 + B \Rightarrow A_2$$

can be done for any  $B \in C$ ,  $+ \in O$  **without changing the relevant behaviour of  $A_1$** .



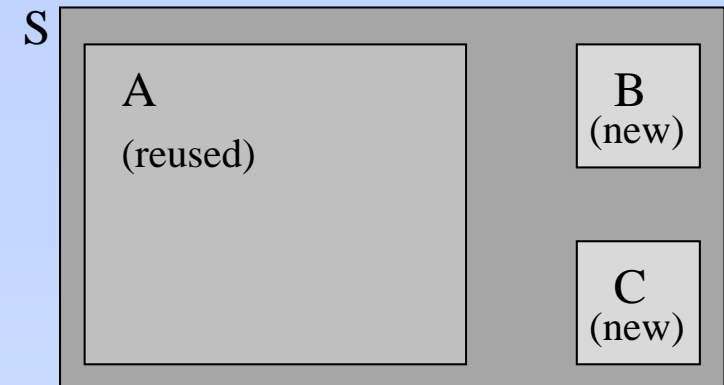
## Linear Effort Property

Given a set of components  $C$  and combinators  $O$ .

Let  $A_1, \dots, A_n$  be component assemblages.

A **design process** using  $C$  and  $O$  to build a system has the **linear effort property** if  $A_1, \dots, A_n$  can be integrated into a system  $S$  with an effort dependent on  $n$  but not on the size of the assemblages:  $I_{\text{effort}}(n)$ .

Total design effort for  $S$  is



$$\text{Deffort}(S) = \text{Deffort}(A_1) + \dots + \text{Deffort}(A_n) + I_{\text{effort}}(n)$$

# Reuse

- Components and resources
- Communication infrastructure
- Application parts and feature reuse
- Design, simulation and prototype environment
- Verification effort



# Predictability

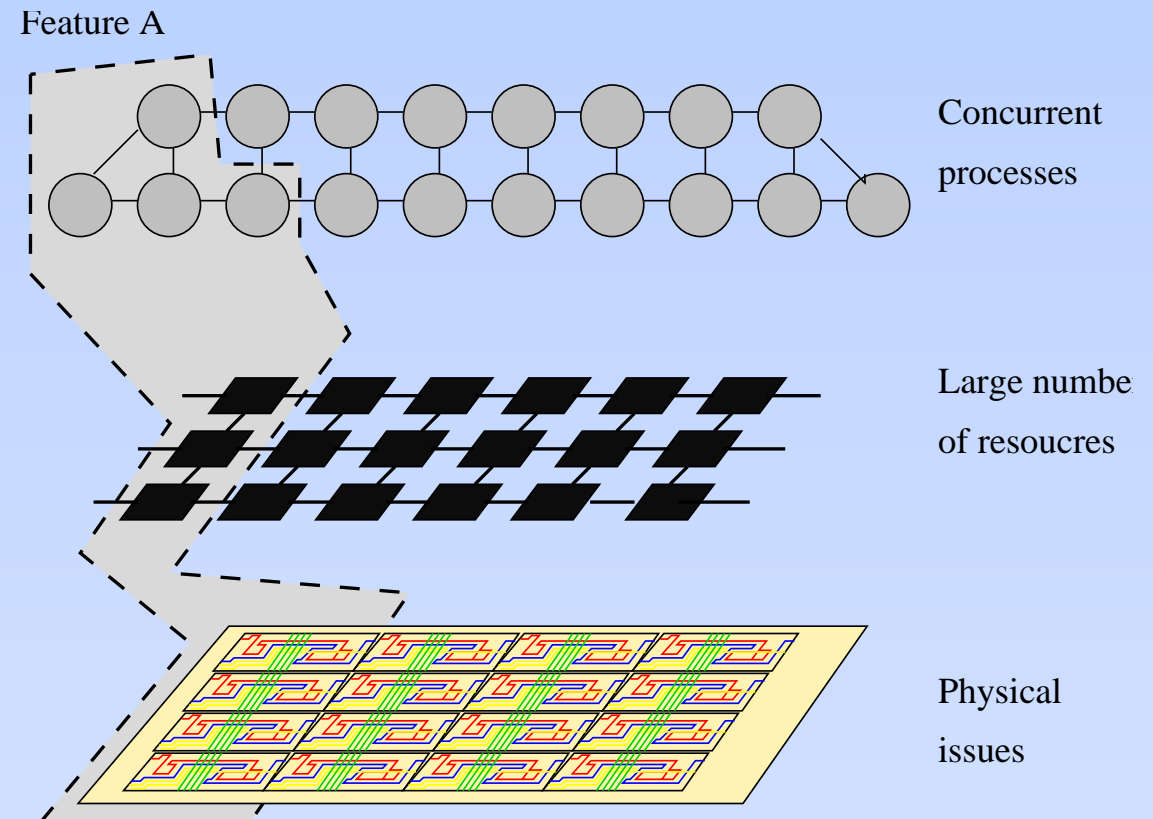
- Communication performance
- Electrical properties
- Design and verification time





# A NoC Based Design Process

- Configuring the platform
- Selecting resources
- Reuse of features
- Evaluation and integration



## Design Methodology - Summary

- A NoC Platform greatly restricts the design space
- It trades in optimality for design efficiency and predictability
- The **arbitrary composability** and the **linear effort properties** provide a scalable platform
- Reuse
- Predictability

Further information: [www.imit.kth.se/info/FOFU/NOC/](http://www.imit.kth.se/info/FOFU/NOC/)

